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- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  < 0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

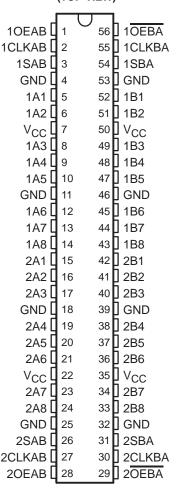
#### description

This 16-bit bus transceiver and register is designed for low-voltage (3.3-V) V<sub>CC</sub> operation.

The SN74LVC16652 consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver.

Complementary output-enable (OEAB and OEBA) inputs control the transceiver functions. Select-control (SAB and SBA) inputs select whether real-time or stored data is transferred. A

#### DGG OR DL PACKAGE (TOP VIEW)



low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the SN74LVC16652.



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# SN74LVC16652 16-BIT BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

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### description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last level configuration.

To ensure the high-impedance state during power up or power down,  $\overline{\text{OEBA}}$  should be tied to  $V_{CC}$  through a pullup resistor and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry holds unused or floating data inputs at a valid logic level.

The SN74LVC16652 is characterized for operation from −40°C to 85°C.



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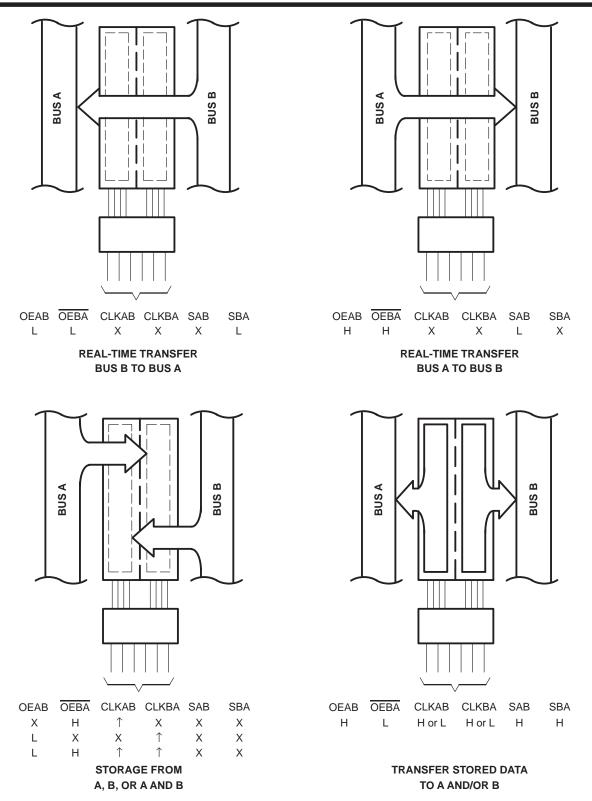
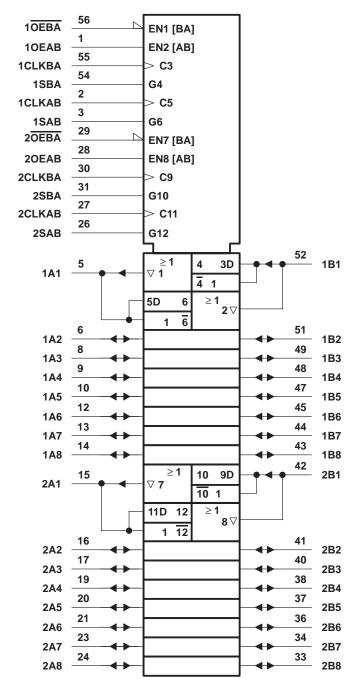


Figure 1. Bus-Management Functions



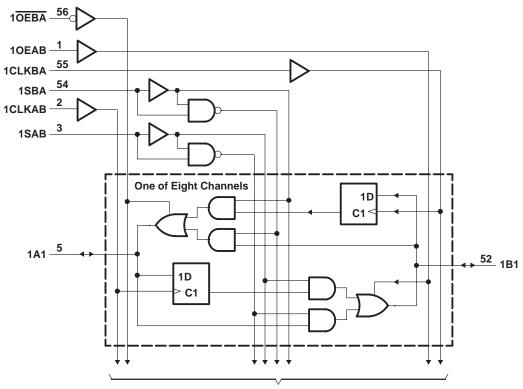
## logic symbol<sup>†</sup>



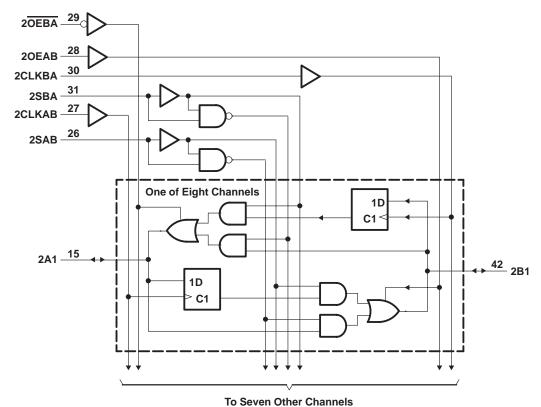
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



# logic diagram (positive logic)



To Seven Other Channels





# SN74LVC16652 16-BIT BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

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#### **FUNCTION TABLE**

	INPUTS					DATA I/O†		OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	$\uparrow$	$\uparrow$	X	X	Input	Input	Store A and B data
Х	Н	$\uparrow$	H or L	X	X	Input	Unspecified <sup>‡</sup>	Store A, hold B
Н	Н	$\uparrow$	$\uparrow$	X‡	X	Input	Output	Store A in both registers
L	X	H or L	$\uparrow$	Χ	X	Unspecified <sup>‡</sup>	Input	Hold A, store B
L	L	$\uparrow$	$\uparrow$	X	X <sup>‡</sup>	Output	Input	Store B in both registers
L	L	Χ	Χ	X	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Χ	Χ	L	X	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	X	Input	Output	Stored A data to B bus
н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and Stored B data to A bus

<sup>†</sup> The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or OEBA inputs. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Supply voltage range, V <sub>CC</sub>	0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> : Except I/O ports (see Note 1)	0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Maximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 3)	): DGG package 1 W
	DL package 1.4 W
Storage temperature range, T <sub>sto</sub>	65°C to 150°C

<sup>§</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This value is limited to 4.6 V maximum.
  - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



<sup>‡</sup> Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered in order to load both registers.

## recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	V
VIH	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		V
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	V
VI	Input voltage		0	VCC	V
٧o	Output voltage		0	VCC	V
lou.	High-level output current			-12	mA
ЮН	riigh-level output current	V <sub>CC</sub> = 3 V		-24	IIIA
lo.	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA
lor	Low-level output current	V <sub>CC</sub> = 3 V		24	IIIA
$\Delta t/\Delta V$	Input transition rise or fall rate		0	10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	v <sub>cc</sub> †	MIN	TYP‡	MAX	UNIT	
		$I_{OH} = -100 \mu\text{A}$	MIN to MAX	V <sub>CC</sub> -0.	.2			
		Jan. — 12 m/s	2.7	2.2			v	
VOH		I <sub>OH</sub> = -12 mA	3	2.4			v	
		$I_{OH} = -24 \text{ mA}$	3	2				
		I <sub>OL</sub> = 100 μA	MIN to MAX			0.2		
VOL		I <sub>OL</sub> = 12 mA	2.7			0.4	V	
		I <sub>OL</sub> = 24 mA	3			0.55		
lį	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6			±5	μΑ	
	A or B ports	V <sub>I</sub> = 0.8 V	3	75				
I <sub>I(hold)</sub>		V <sub>I</sub> = 2 V	] 3	-75			μΑ	
		V <sub>I</sub> = 0 to 3.6 V	3.6			±500		
loz§		$V_O = V_{CC}$ or GND	3.6			±10	μΑ	
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6			40	μΑ	
Δlcc		One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V			500	μΑ	
Ci	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3		3		pF	
C <sub>io</sub>	A or B ports	$V_O = V_{CC}$ or GND	3.3		7		pF	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.



 $<sup>\</sup>ddagger$  All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C. § For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

# SN74LVC16652 16-BIT BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

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# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	100	0	80	MHz
t <sub>W</sub>	Pulse duration, CLK high or low		4.5		4.5		ns
t <sub>su</sub>	Setup time, A or B before CLKAB↑ or CLKBA↑	Data high or low	5		5		ns
t <sub>h</sub>	Hold time, A or B after CLKAB↑ or CLKBA↑	Data high or low	0		0		ns

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

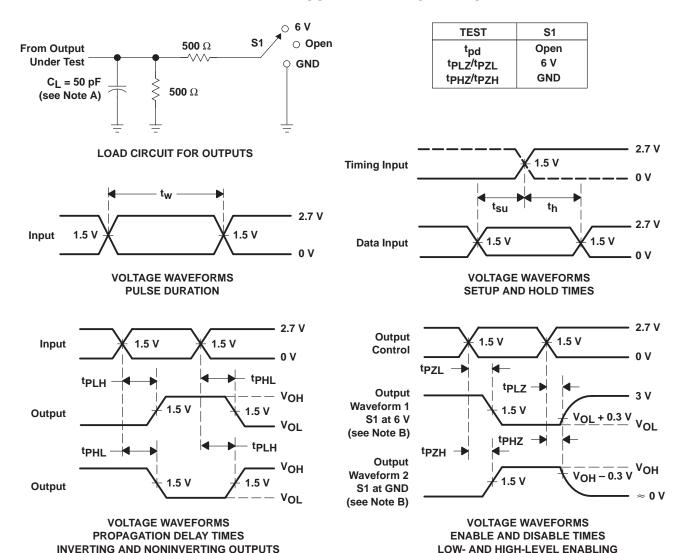
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 2.7 V		UNIT
	(INFOT)	(001701)	MIN	MAX	MIN	MAX	
f <sub>max</sub>			100		80		MHz
	A or B	B or A	1.5	7		8	
t <sub>pd</sub>	CLKAB or CLKBA	A or B	1.5	8.5		9.5	ns
'	SAB or SBA		1.5	8.5		9.5	
t <sub>en</sub>	OE or OE	A or B	1.5	8		9	ns
<sup>t</sup> dis	OE or OE	A or B	1.5	8.5		9.5	ns

# operating characteristics, $V_{CC}$ = 3.3 V, $T_A$ = 25°C

PARAMETER			TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Dower dissination conscitance per transceiver	Outputs enabled	C <sub>1</sub> = 50 pF. f = 10 MHz	25	nE
	Power dissipation capacitance per transceiver	Outputs disabled	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	4	pF



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



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